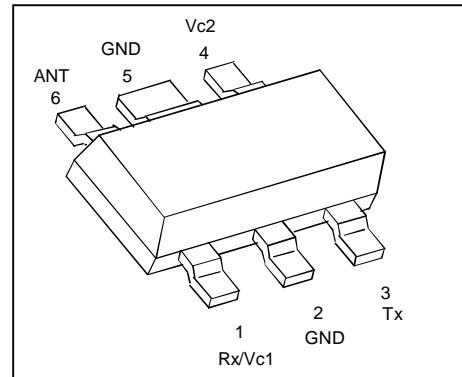


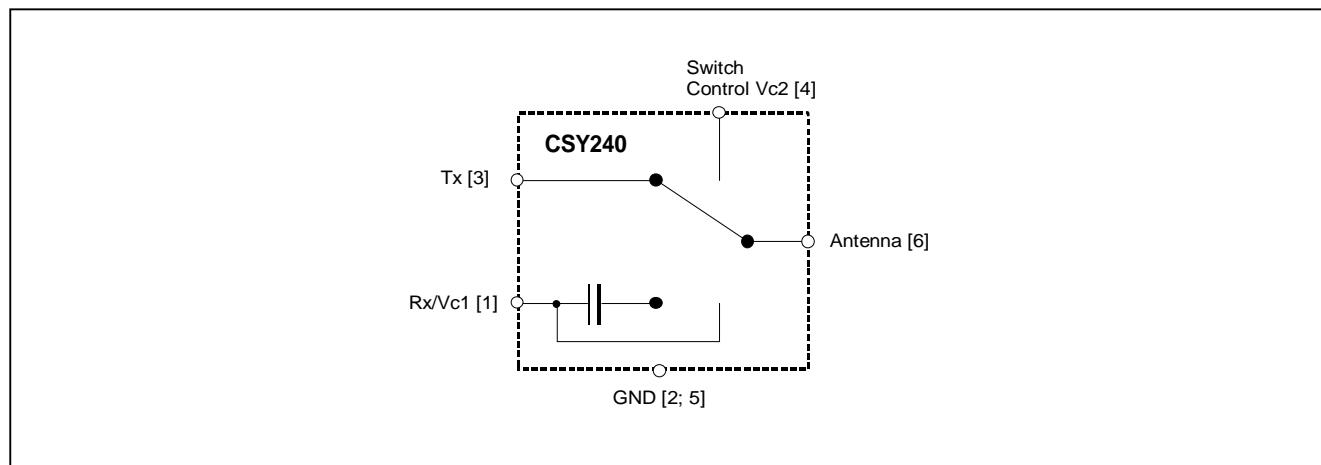
GaAs MMIC**Preliminary Data**

- TX/RX- and diversity switch for mobile communications and 2.45GHz WLAN applications
- Low insertion loss
- High TX/RX isolation
- Frequency range 0.5 - 3.0 GHz
- High input power capability
- Very low rise / fall time
- Miniature package MW6 based on SOT23



ESD: Electrostatic discharge sensitive device,
observe handling precautions!

| Type | Marking | Ordering code (taped) | Package 1) |
|---------|---------|--------------------------|------------|
| CSY 240 | S1 | Q62702-S2000 | MW-6 |

**Maximum ratings**

| Characteristics | Symbol | | Unit |
|--|-------------------|------------|------|
| Control voltage range | V_{c1} / V_{c2} | 0....-7 | V |
| Channel temperature | T_{Ch} | 150 | °C |
| Storage temperature range | T_{stg} | -55...+150 | °C |
| Total power dissipation ($TS \leq tbd^{\circ}\text{C}$) 2) | P_{tot} | tbd. | mW |

Thermal resistance

| Characteristics | Symbol | | Unit |
|-------------------------------|---------------|-------------|-------------|
| Channel-soldering point (GND) | R_{thChS} | \leq tbd. | K/W |
| Channel-ambient ³⁾ | R_{thChA} | < tbd. | K/W |

- 1) Dimensions see page 5.
 2) Please care for sufficient heat dissipation on the pcb!
 3) Package mounted on alumina 15 mm x 16.7 mm x 0.7 mm

Electrical characteristics

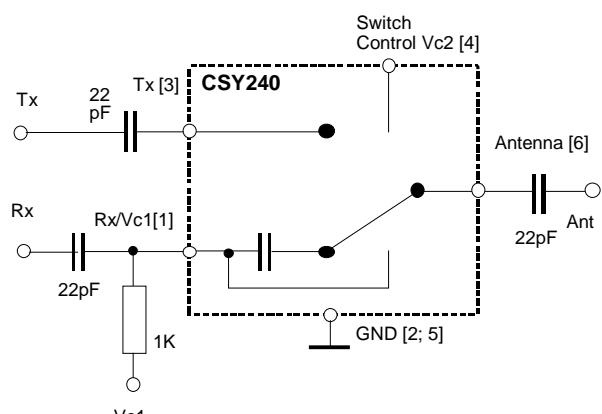
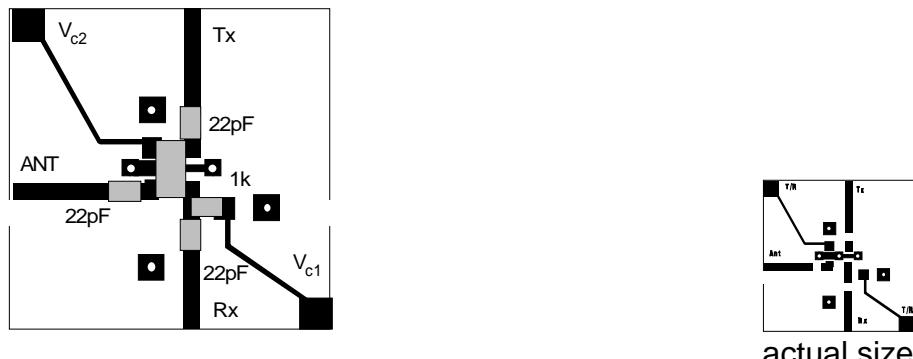
$T_A = 25^\circ\text{C}$ $RS = RL = 50\Omega$ $P_{IN} = 10\text{dBm}$ unless otherwise specified

| Characteristics | Symbol | min | typ | max | Unit |
|---|---------------|-------------|---------------------|-------------|---------------|
| Control current $V_c = -5\text{V}$ | I_c | - | 20 | - | μA |
| Insertion Loss Tx - Path $V_{c1} = 0\text{V}; V_{c2} = -5\text{V}; f = 900\text{MHz}$ $f = 1.8\text{GHz}$ $f = 2.5\text{GHz}$ | IL_{Tx} | - - - | 0.3 0.5 0.7 | - - - | dB |
| Insertion Loss Rx - Path $V_{c1} = -5\text{V}; V_{c2} = 0\text{V}; f = 900\text{MHz}$ $f = 1.8\text{GHz}$ $f = 2.5\text{GHz}$ | IL_{Rx} | - - - | 0.35 0.55 0.8 | - - - | dB |
| Input- / Output return loss Tx - Path $V_{c1} = 0\text{V}; V_{c2} = -5\text{V}; f = 900\text{MHz}$ $f = 1.8\text{GHz}$ $f = 2.5\text{GHz}$ | RL_{Tx} | - - - | 20 20 15 | - - - | dB |
| Input- / Output return loss Rx - Path $V_{c1} = -5\text{V}; V_{c2} = 0\text{V}; f = 900\text{MHz}$ $f = 1.8\text{GHz}$ $f = 2.5\text{GHz}$ | RL_{Rx} | - - - | 16 17 14 | - - - | dB |
| Tx- / Rx - Isolation ¹⁾ $V_{c1} = 0\text{V}; V_{c2} = -5\text{V}; f = 900\text{MHz}$ $f = 1.8\text{GHz}$ $f = 2.5\text{GHz}$ | ISO_{TxRx} | - - - | 28 22 19 | - - - | dB |

| Characteristics | Symbol | min | typ | max | Unit |
|---|---------------|-------------|----------------|-------------|-------------|
| Ant / Rx - Isolation ¹⁾ Vc1 = 0V; Vc2 = -5V; f = 900MHz f = 1.8GHz f = 2.5GHz | ISO_{AntRx} | - - - | 28 22 19 | - - - | dB |
| Tx- / Ant- Isolation ¹⁾ Vc1 = -5V; Vc2 = 0V; f = 900MHz f = 1.8GHz f = 2.5GHz | ISO_{TxAnt} | - - - | 29 24 19 | - - - | dB |
| Output power at 1dB gain compression (Tx- Path) Vc1 = 0V; Vc2 = -5V; f = 900MHz | P_{-1dB} | - | 30 | - | dBm |

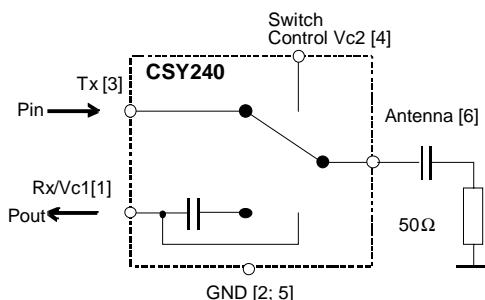
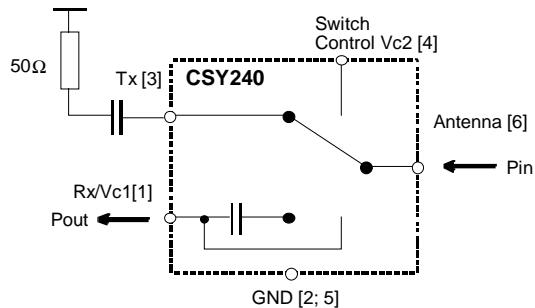
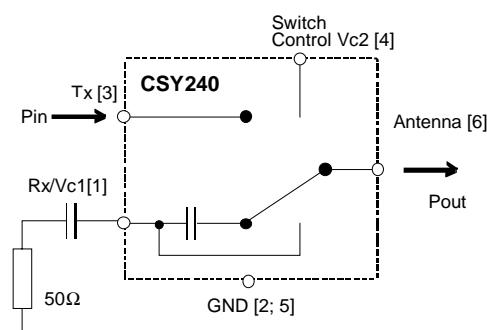
1) See page 4 for definition

| Characteristics | Symbol | min | typ | max | Unit |
|--|---------------|------------|------------|------------|-------------|
| Input Power at 1dB gain compression (Rx - Path) Vc1 = -5V; Vc2 = 0V f = 900MHz | P_{-1dBin} | - | 31.5 | - | dBm |
| Third order output intercept point (Tx - path) two-tone intermodulation test Vc1 = 0V; Vc2 = -5V | IP_3 | - - | tbd. | - - | dBm |
| Third order input intercept point (Rx - path) two-tone intermodulation test Vc1 = -5V; Vc2 = 0V | IP_{3in} | - - | tbd. | - - | dBm |

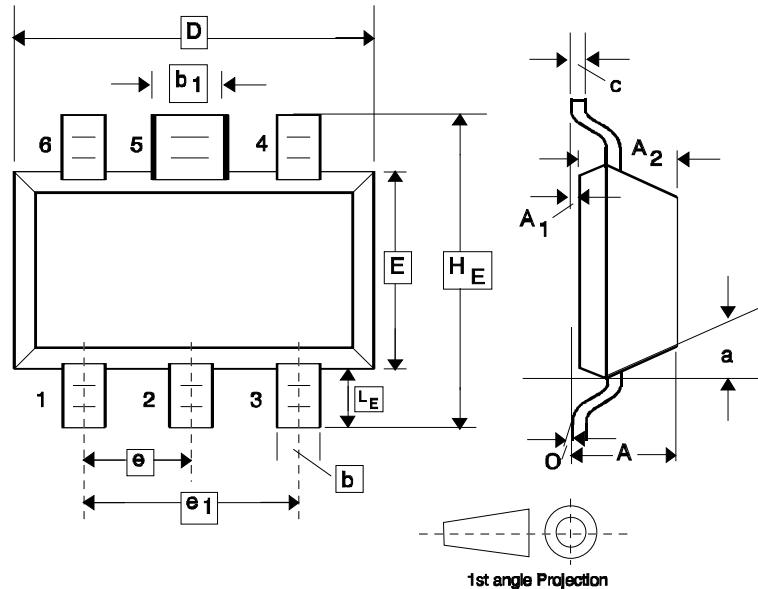
Test and application circuit:**Layout of application board:**

PCB - data: Glass fiber teflon board (double sided) TACONIC TLX-9-0150-CH/CH

$\epsilon_r = 2.45$ thickness = 0.4mm

Test - conditions for isolation measurements:**Tx / Rx Isolation****Ant / Rx Isolation****Tx / Ant Isolation**

Semiconductor Device Outline MW-6



| Dim. | min. | nom. | max. | Gradient | Remark |
|----------------|------|------|------|----------|--------|
| A | | | 1.1 | | |
| A ₁ | | | 0.1 | | |
| A ₂ | | | 1.0 | | |
| b | | 0.3 | | | |
| b ₁ | | 0.6 | | | |
| c | 0.08 | | 0.15 | | |
| D | 2.8 | | 3.0 | | |
| E | 1.2 | | 1.4 | | |
| e | | 0.95 | | | |
| e ₁ | | 1.9 | | | |
| H _E | | | 2.6 | | |
| L _E | | | 0.6 | | |
| a | | | | max 10° | 1 |
| q | | | | 2°...30° | |

- Applicable on all case top sides

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